

Figures

2025-01-01 10:00:00

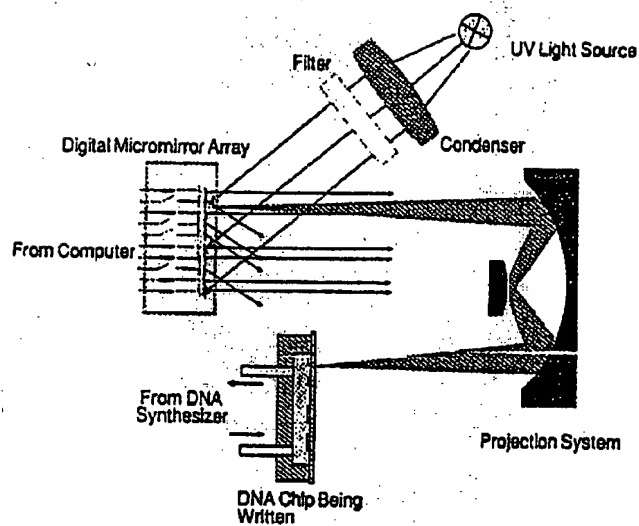


Fig. 1

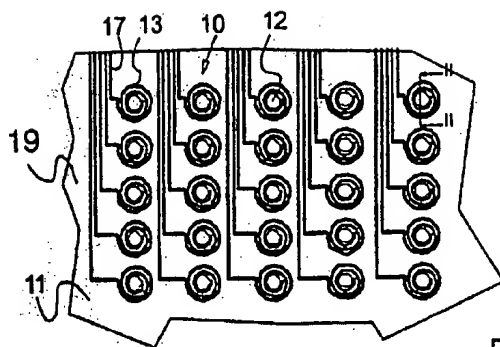


Fig. 2

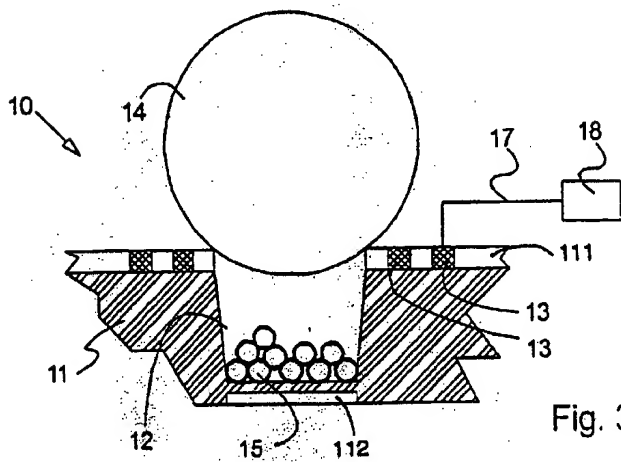


Fig. 3

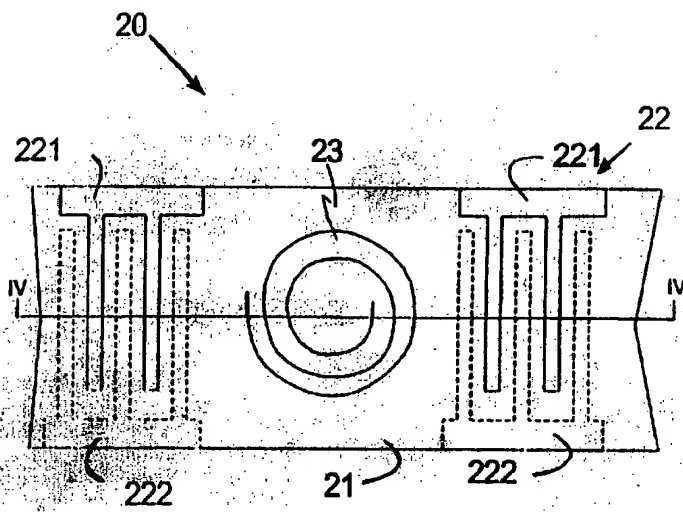


Fig. 4

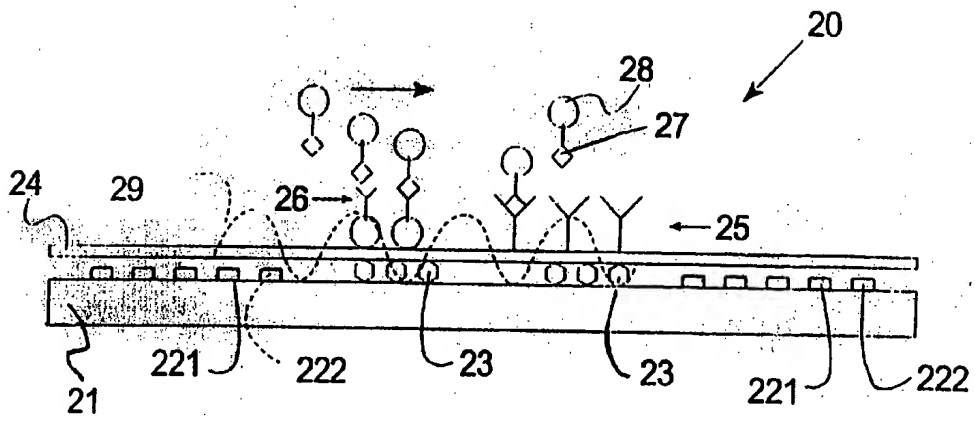


Fig. 5

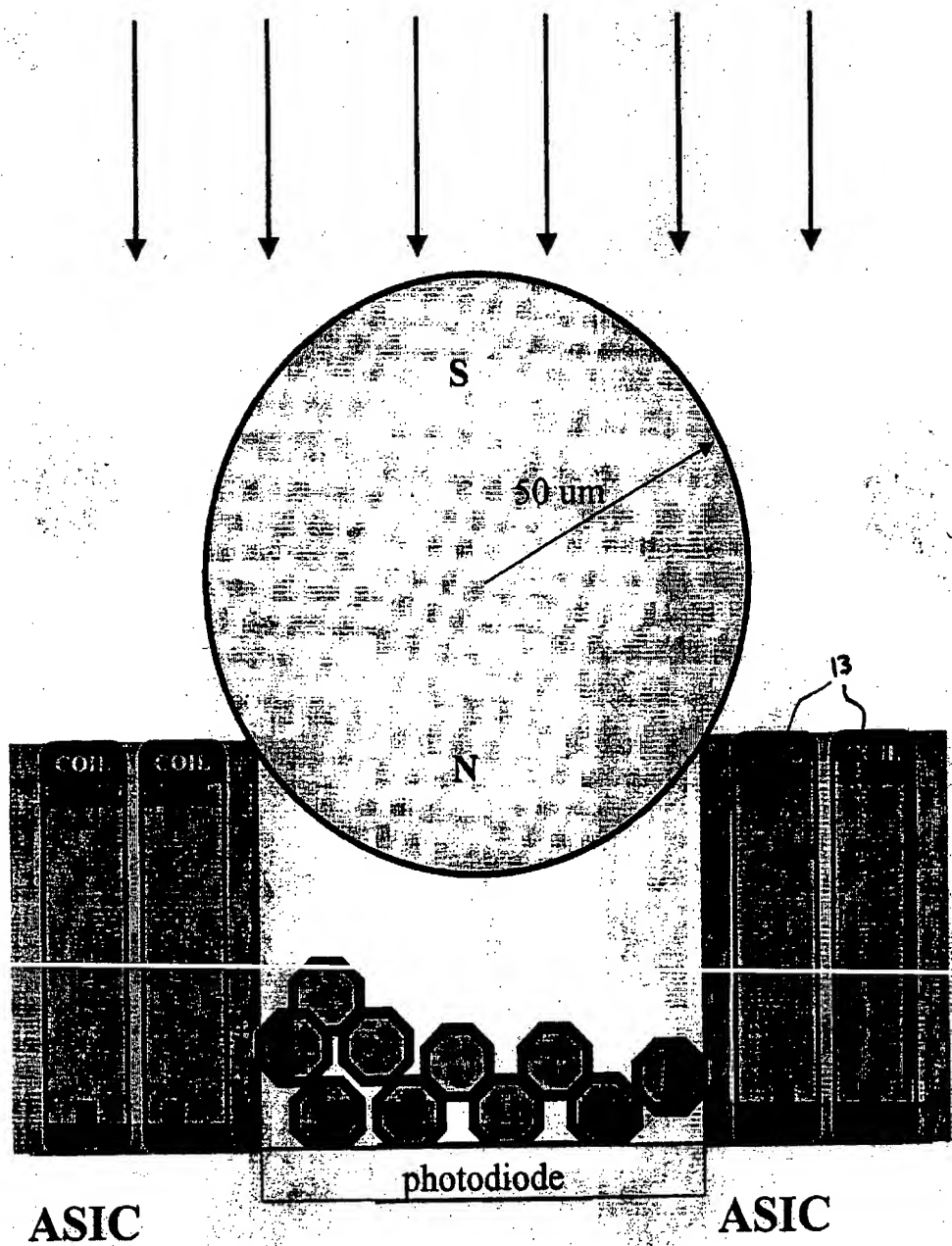


Figure 6

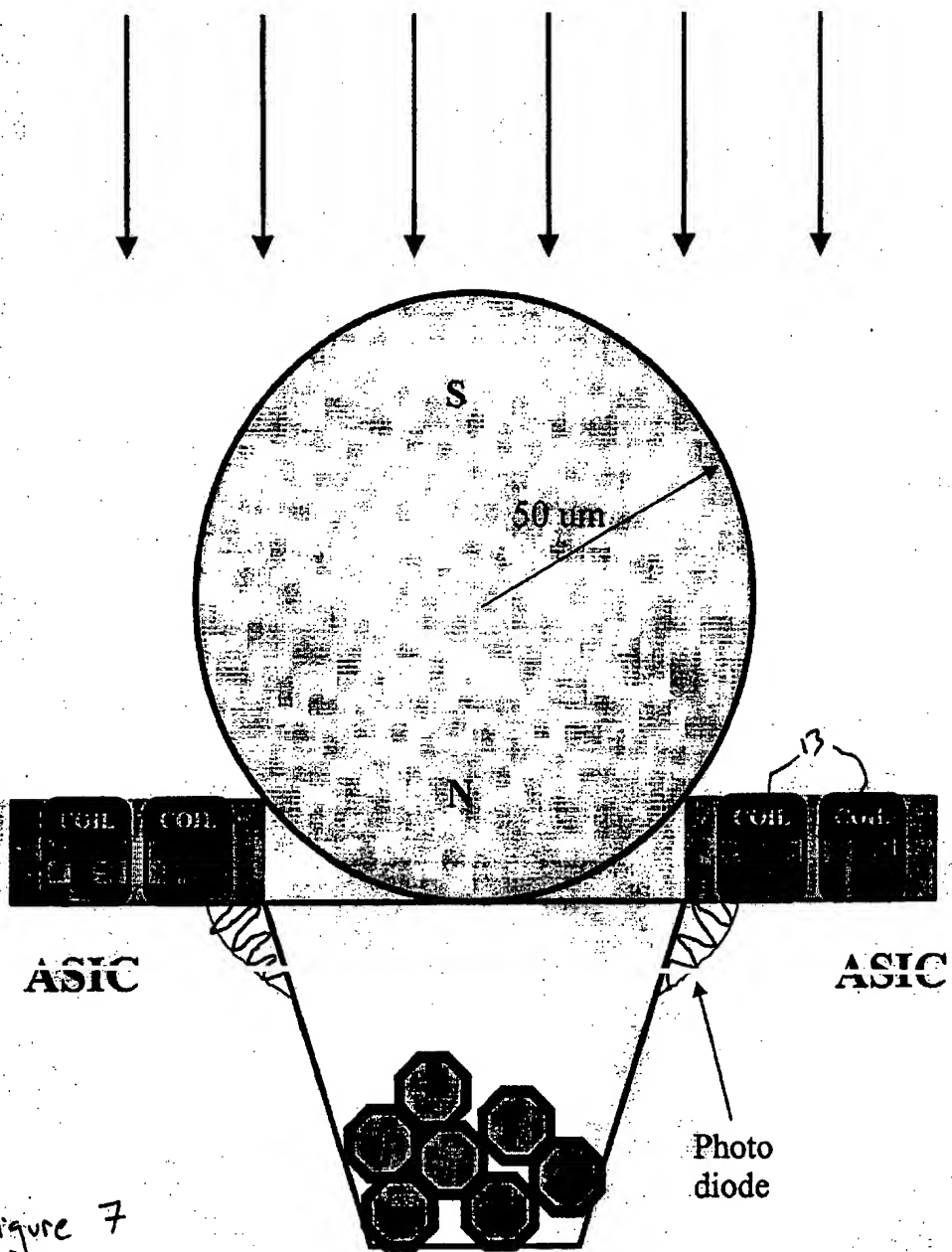


Figure 7

BEAD IN BEAD-HOLDER POCKET ON NON-SENSOR CHIP

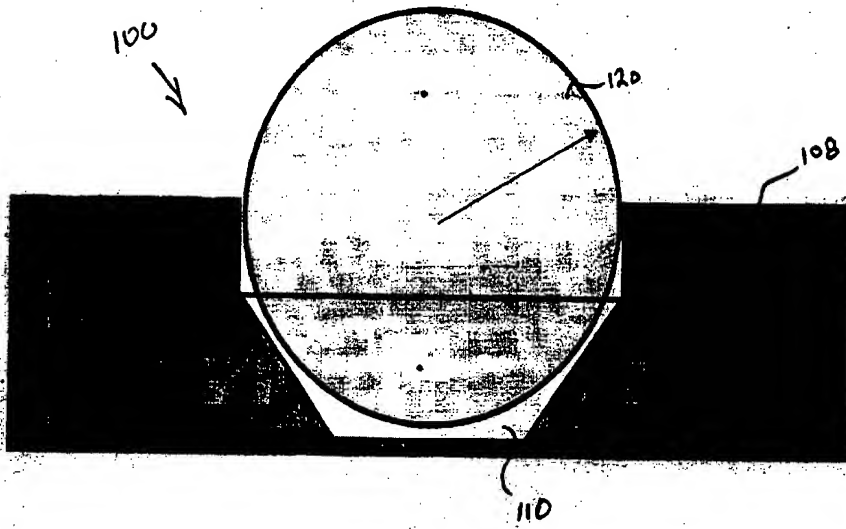


Figure 8

2025 RELEASE UNDER E.O. 14176

Particle in pocket, in place over sensor

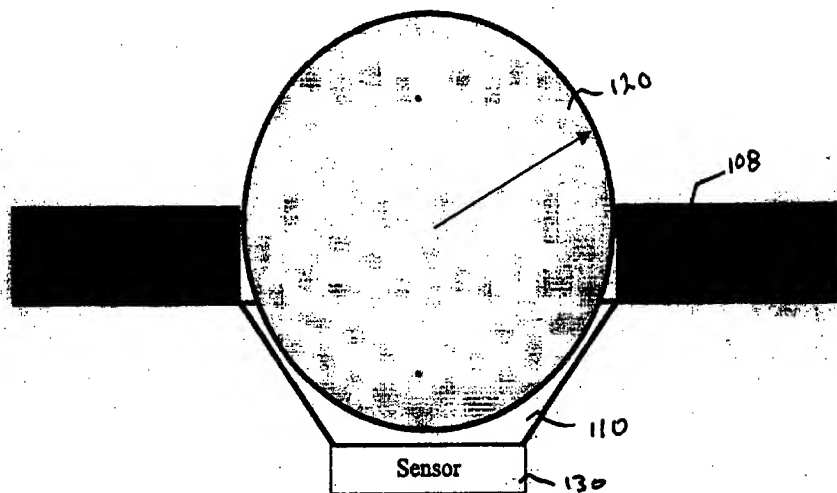


Figure 9

A few examples of some other sensor locations

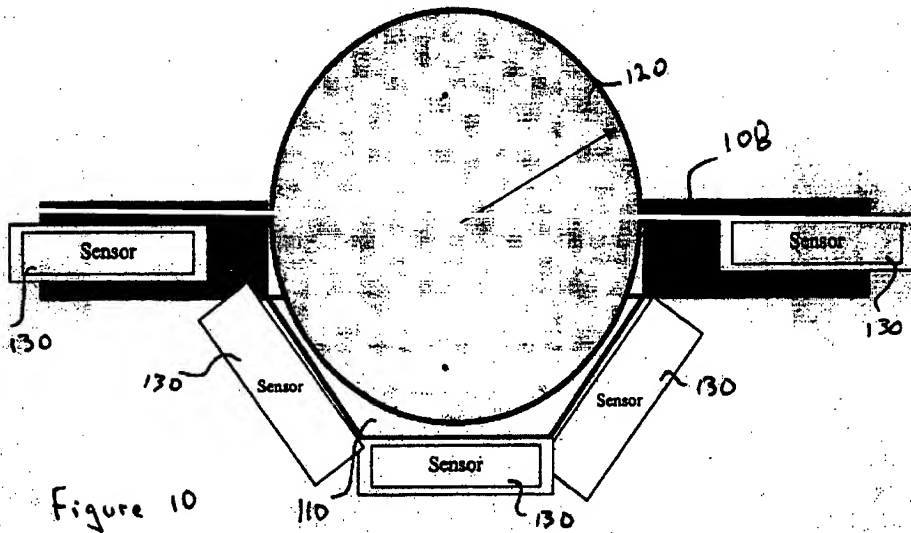
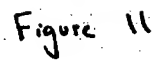
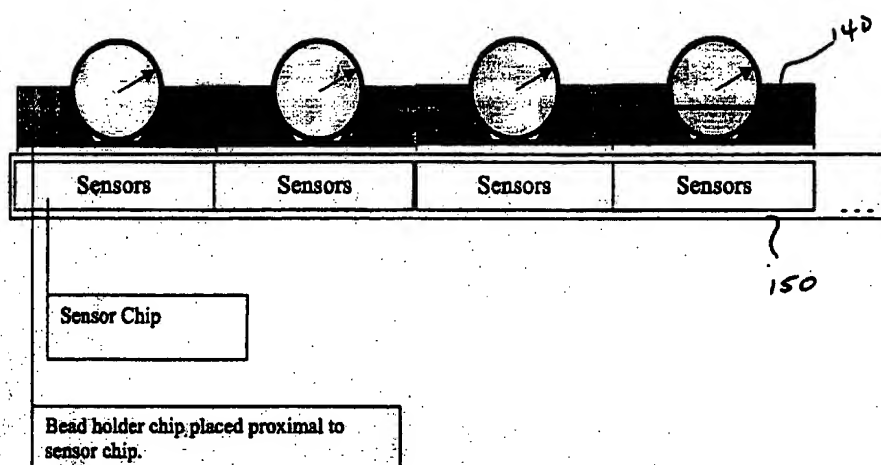


Figure 10

(Faint, illegible text from bleed-through)



SEPARATELY MANUFACTURED/HANDLEABLE POCKET CHIP AND SENSOR CHIP



Example Sensors : a commercially available CMOS photodiode array

Figure 12

A key aspect is the pre-determined positioning of particles; this allows positioning with respect to sensors:

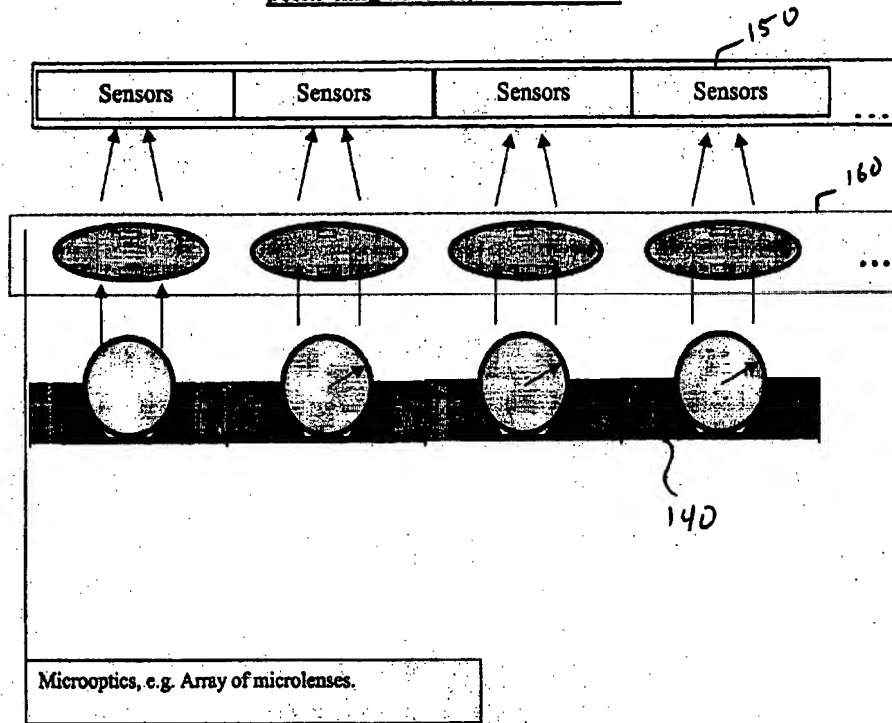


Figure 13

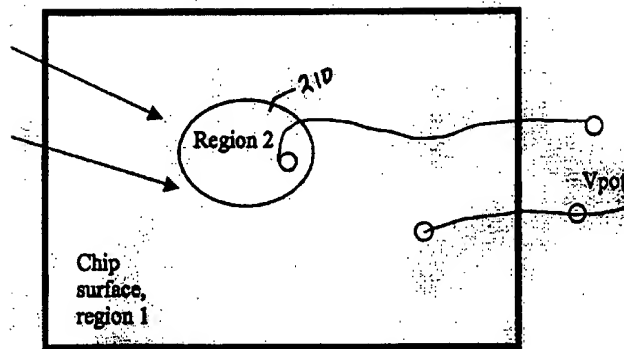


Figure 14. Top view of a silicon surface with a doped region (region 2). The electric circuit is completed by Vpot, using two leads contacting each region.

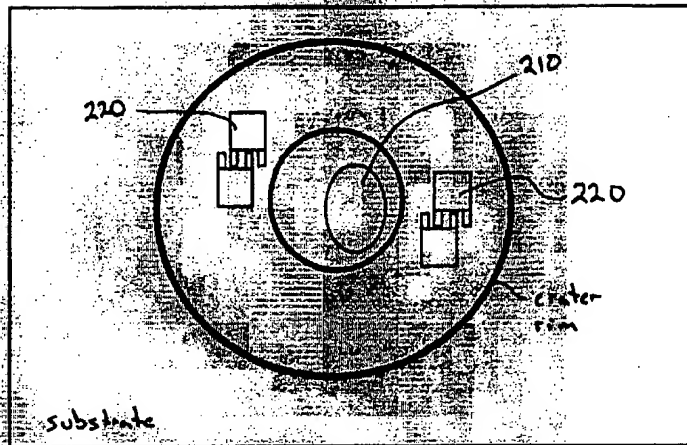


Figure 15. A crater from above, with a doped region (e.g., photodiode) on the bottom and also two circuits with capacitive detection capability on the sloping insides of the crater.

V_{port}

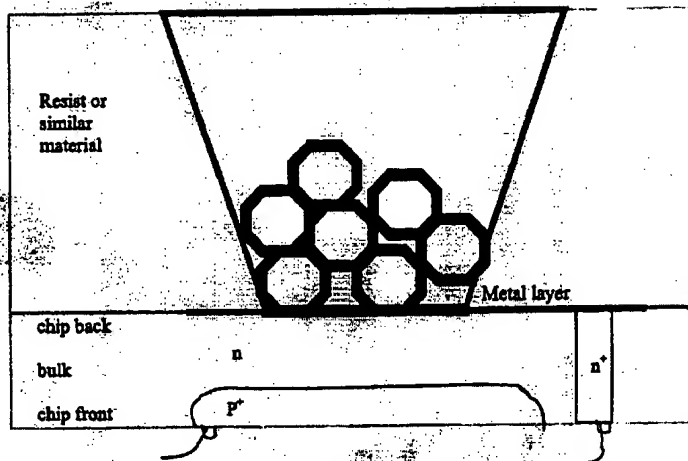


Figure 16

2025 RELEASE UNDER E.O. 14176